

Customer Waiver Request

Waiver Number: CW120345 Date Issued: 3/1/2012 Product(s) Affected: PE42440 Quantity or Lot/Date Codes Waiver Applies to: Applies to all part number identified PE42440MLIBB-Z Expiration Date (If Applicable): N/A	Contact: Rick Sanford Title: Director, Sales Operations Phone: 858-731-9461 Fax: 858-731-9499 Email: rsanford@psemi.com
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Non-Conformance:

<input type="checkbox"/> Wafer Fabrication Process <input type="checkbox"/> Electrical Performance <input type="checkbox"/> Visual Non-Conformance <input type="checkbox"/> Assembly Process	<input type="checkbox"/> Shipping/Labeling <input checked="" type="checkbox"/> Non-Standard Manufacturing Flow <input type="checkbox"/> Material <input type="checkbox"/> Other
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Description on Non-Conformance:

PE42440 product manufactured and tested at Hana Semiconductor Co., Ltd. (Ayutthaya, Thailand) will be manufactured at Unisem Berhad (Ipoh, Malaysia) and tested at Peregrine Semiconductor Corp. (San Diego, California, USA). This part will ship as the PE42440MLBB-Z.
Details of the package BOM differences are on the following page.

Justification:

The Hana facility at Ayutthaya has been temporarily shut down due to flooding.

Customer Approval:

<input type="checkbox"/> Waiver Accepted <input type="checkbox"/> Waiver Denied	Name:	
	Title:	
	Company:	
	Date:	
	Signature:	
Customer Comments:		

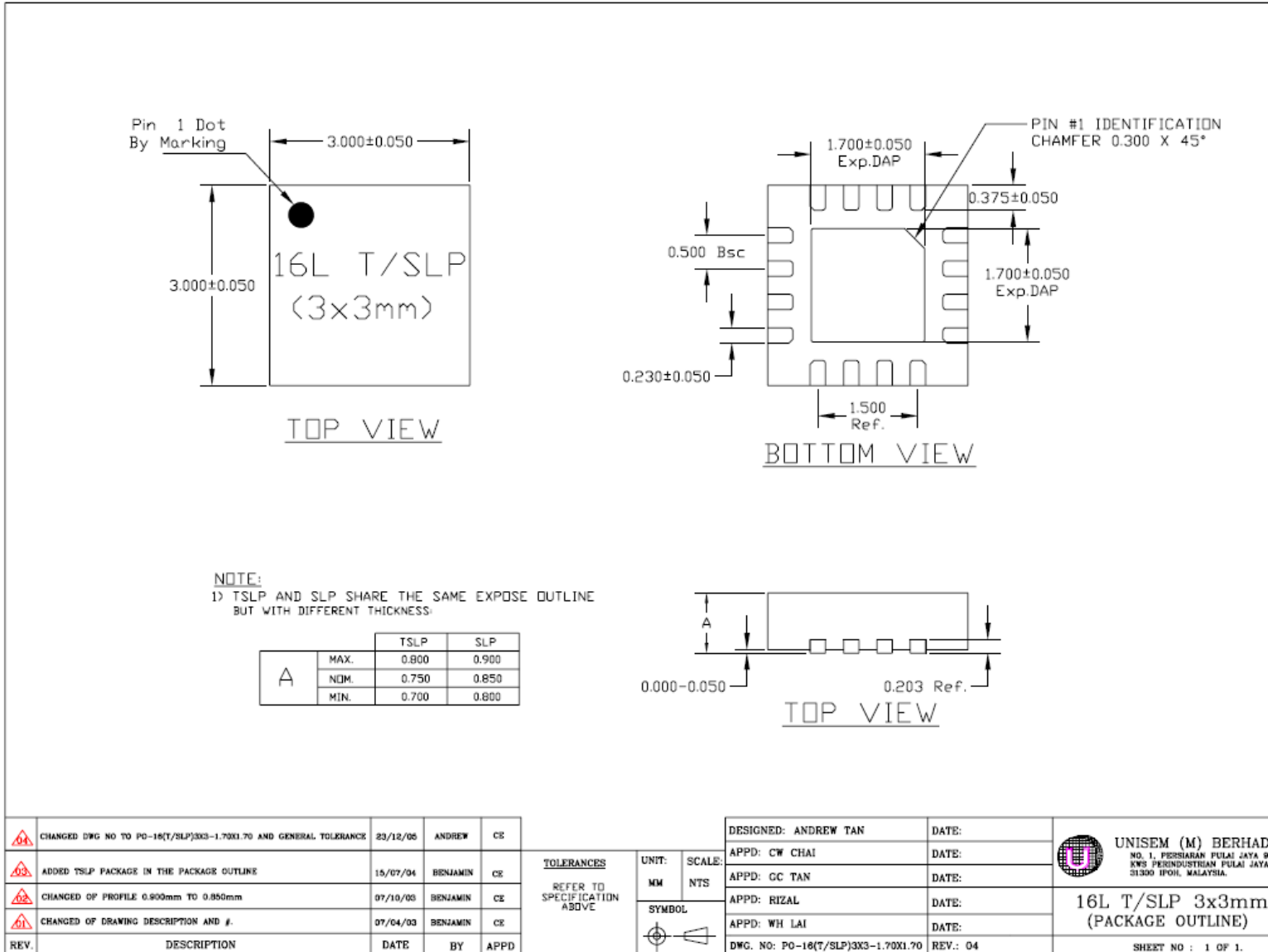
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Unisem vs. Hana BOM comparison for 16L 3x3 QFN

Vendor	Unisem	Hana
Package Name	16L-TSLP	16L-TSLP
Style	TSLP or TQFN	TSLP or TQFN
Peregrine BOM #	19-0128	19-0133
Lead Count	16	16
Exposed Pad Size (mm)	1.70x1.70	1.70x1.70
Die Attach Paddle Size (mm)	1.90x1.90	1.90x1.90
Lead Frame Material	Cu base with Pad Ring Ag	Cu with NiPdAu plating
Lead Plating	Sn	NiPdAu
Die Attach Epoxy	CRM1076DJ	400195: Ablestick Abletherm 8600
Mold Compound	Sumitomo G770HCD	450176: Hitachi CEL9220HF
MSL	1	1

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Unisem Package Drawing



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Hana Package Drawing

REV	DESCRIPTION	DATE
A	ORIGINAL ISSUE	JUN 20'05

TOP VIEW

BOTTOM VIEW

SYMBOL	COMMON					
	DIMENSIONS MILLIMETER			DIMENSIONS INCH		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	SEE VARIATIONS					
A3	0.195	0.203	0.211	0.0077	0.008	0.0083
b	0.18	0.23	0.30	0.007	0.009	0.012
D	2.95	3.0	3.05	0.116	0.118	0.120
E	2.95	3.0	3.05	0.116	0.118	0.120
e	0.50 BSC			0.020 BSC		
L	0.35	0.40	0.45	0.014	0.016	0.018

SYMBOL	VARIATIONS "A"					
	DIMENSIONS MILLIMETER			DIMENSIONS INCH		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
OPTION 1	0.70	0.75	0.80	0.027	0.029	0.031
OPTION 2	0.85	0.90	0.95	0.033	0.035	0.037

SEATING PLANE

SIDE VIEW

SYMBOL	D2/E2			D2/E2		
	DIMENSIONS MILLIMETER					
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
OPTION 1	1.50/1.50	1.625/1.625	1.75/1.75	0.059/0.059	0.064/0.064	0.069/0.069

ORIGINAL COPY

29 JUN 2005

NOTES:

1. DIMENSION AND TOLERANCING CONFORM TO ASME Y14.5M-1994.
2. CONTROLLING DIMENSIONS : MILLIMETER. CONVERTED INCH DIMENSION ARE NOT NECESSARILY EXACT.
3. DIMENSION b APPLIES TO METALLIZED TERMINAL AND IS MEASURED BETWEEN 0.15mm AND 0.30mm FROM THE TERMINAL TIP, IF THE TERMINAL HAS THE OPTIONAL RADIUS ON THE OTHER END OF THE TERMINAL, THE DIMENSION b SHOULD NOT BE MEASURED IN THAT RADIUS AREA

	DRAWN BY: EKAWIT B. JUN 2005	TITLE: QFN 3X3 (16LD) PACKAGE OUTLINE DRAWING
	CHECKED BY: NOPPADOL K. JUN 2005	DATE: JUN 20'05
APPROVED BY: THANAPONG JUN 2005	REF. NO.: JEDEC MO-220	SCALE: NOT TO SCALE
APPROVED BY: N/A	DWG. NO. N016PD-0203	SHEET 1 OF 1

FILE NAME : QFN (3 X 3) 16 LD